ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Compos © Copyright 2005. IPC international and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ. http://www.ipc.org/IPC-175x Form Typ. Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				aterials and	ials and Mfg Information			
Supplier Inform	nation														
Company name* Company				npany unique ID			Unique ID Authority				Resp	Response Date*			
nsemi										2023	2023-06-08				
Contact Name		Title - Contact]	Phone - Contact*				Ema	Email - Contact*				
Product-Env-Stew	ards	Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com				
uthorized Repres	entative*	Title - Representative]	Phone - Representative*				Emai	Email - Representative*				
Product-Env-Stew	ards	Product Enviro Compliance				NA				Proc	Product-Env-Stewards@onsemi.com				
Request	Requester Item Number		Mfr Item Number Mfr Item Name				Effective Date	e Versi	on	Manufacturing Site		Weight*	UOM	Unit Type	
		NCP5369MNR2G INTEGRATE		INTEGRATED D	DRMOS		2023-06-08	-06-08 PHA		РНА		98.45	mg	Each	
Ianufacturing	Process Informati	on												·	
Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 I		J-STD-020 M	SL Rating	Peak Process Body Temperatu		re Max Time at	Peak Tempe	erature Numb	er of Reflow Cy	cles		
Matte Tin (Sn) - annealed		CU Alloy 3		3		260 C		30	se	conds 3					
omments															
TTENTION: MS	L 3 Rated item requires	Bake and D	ry Pack (afte	r electrical test)											
or more informati	on regarding material co	omposition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	8.0	mg	Supplier	Silicon (Si)	7440-21-3		8	mg
Die Attach Solder	12.0	mg	Supplier	Silver (Ag)	7440-22-4		0.3	mg
			A	Lead (Pb)	7439-92-1	7a	11.1	mg
			Supplier	Tin (Sn)	7440-31-5		0.6	mg
Lead Frame	50.35	mg	Supplier	Silver (Ag)	7440-22-4		1.3594	mg
			Supplier	Tin (Sn)	7440-31-5		0.1208	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0957	mg
			Supplier	Chromium (Cr)	7440-47-3		0.146	mg
			Supplier	Copper (Cu)	7440-50-8		48.628	mg
Mold Compound-Black	26.0	mg		Epoxy resin	proprietary data		1.222	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.6	mg
			Supplier	Carbon Black (C)	1333-86-4		0.026	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		20.93	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.222	mg
Plating	1.8	mg	Supplier	Tin (Sn)	7440-31-5		1.8	mg
Wire Bond	0.3	mg	Supplier	Palladium (Pd)	7440-05-3		0.003	mg
			Supplier	Copper (Cu)	7440-50-8		0.297	mg